ABSTRACT

HIGH PERFORMANCE SYSTEM-ON-CHIP USING POST PASSIVATION PROCESS

The present invention extends the above referenced continuation-in-part application by in addition creating high quality electrical components, such as inductors, capacitors or resistors, on a layer of passivation or on the surface of a thick layer of polymer. In addition, the process of the invention provides a method for mounting discrete electrical components at a significant distance removed from the underlying silicon surface.

FIGURE 1 IS SUGGESTED FOR PUBLICATION